Supporting Information

Enhanced thermal conductivity of silione composites filled with few-layered hexagonal boron nitride

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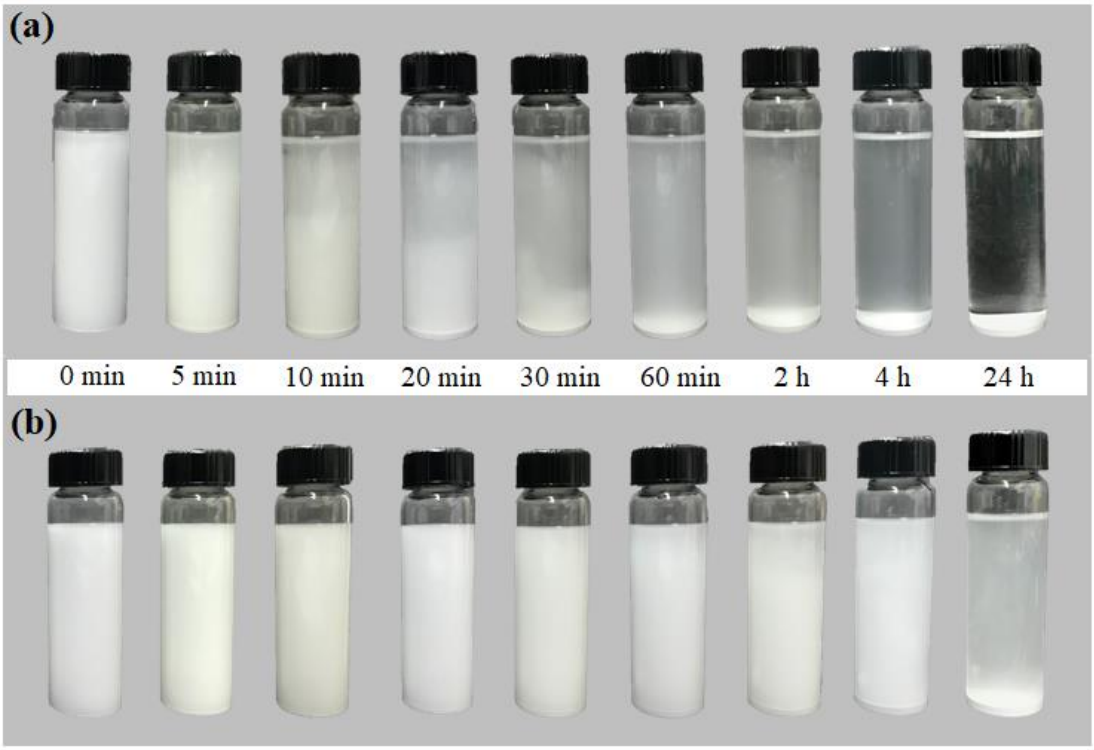

Figure S1. Photo images of (a) pristine h-BN and (b) FL-hBN solution after different resting time.

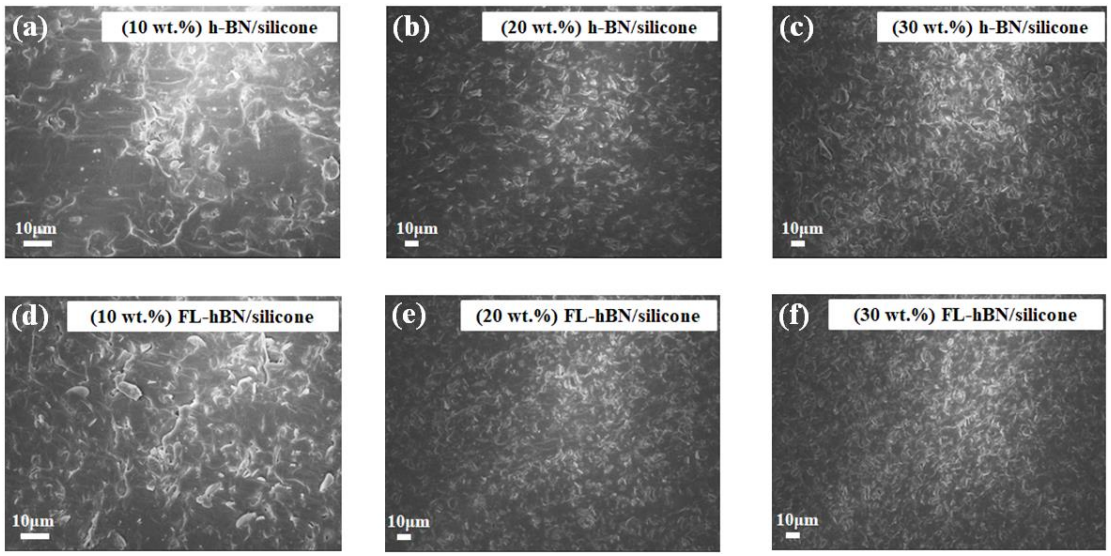

Figure S2. (a)-(c) SEM images of h-BN/silicone composites with powder loading of 10 wt%, 20 wt%, 30 wt% ; (d)-(f) SEM images of FL-hBN/silicone composites with powder loading of 10 wt%, 20 wt%, 30 wt%.

Table S1. FWHM, Lc and La of h-BN and FL-hBN.

	FWHM(002)(°)	**Lc (002)(Å)**	**La (100)(Å)**
h-BN	0.3191	256.2	228.8
FL-hBN	0.4130	197.9	213.5